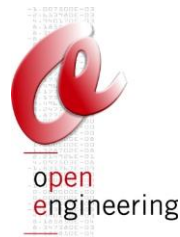


Design of Reliable MEMS for Space Applications Using Multiphysic Simulation Tools

Pascal De Vincenzo & Stéphane Paquay
Open Engineering, Angleur, Belgium

Olivier Letraon
ONERA, Chatillon, France



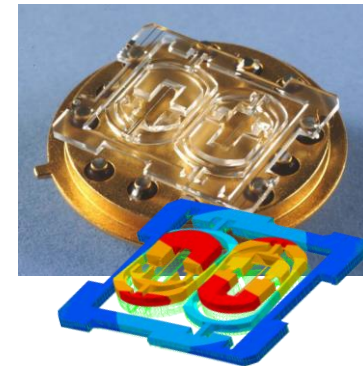
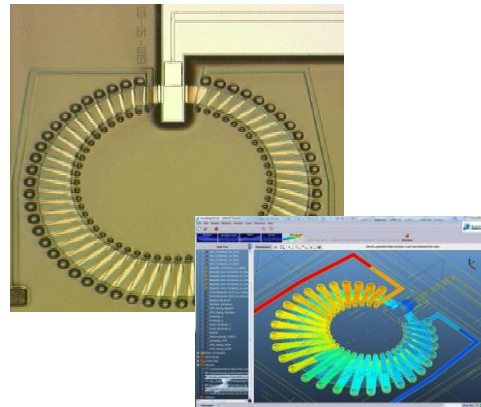
□ Introduction

- Open Engineering & OOFELIE::Multiphysics
- Uncertainties quantification
- General microsystems applications

□ Detailed applications

- Accelerometers: VIA & DIVA
- MEMS Electromagnetic actuator

□ Conclusions



With courtesy of ONERA

Introduction

Open Engineering & OOFELIE::Multiphysics

- ❑ OE develops and sells simulation software
- ❑ OE provides services

Sensors, Actuators & Optics

Fluid Structure Interaction

Sensor & Actuator Current Techniques

Transduction techniques : sensing

- Capacitive
- Piezoresistive
- Thermal
- Piezoelectric

Transduction techniques : actuation

- Capacitive
- Magnetic
- Thermal
- Piezoelectric (bimorph)

Hypersonic Fluid Structure Interaction

Strongly coupled integrated F.S.I.

ESA

open engineering

Oofelie fully addresses Today's Advanced Design Needs

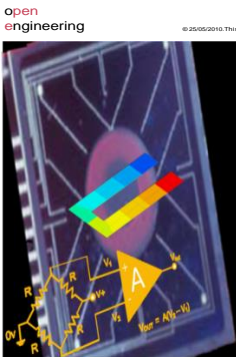
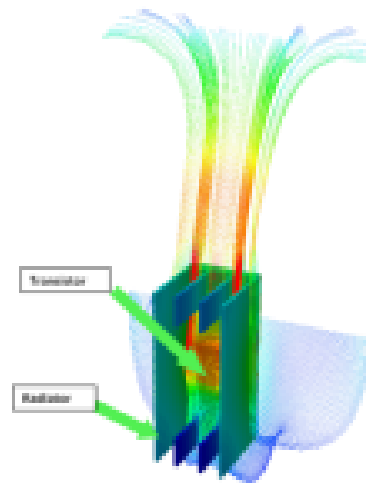
OOFELIE Multiphysics Fluid Elements for Full Multiphysics Linking

OOFELIE for structure and ... for fluids!

Integrate easily flows in your 2D and 3D models!

Possible multiphysics couplings with thermal dissipations, structure deformations, piezoelectrics ...

open engineering



MEMS Design of Vibrating Inertial Accelerometers

- Size reduction & new manufacturing technologies
- Needs strongly coupled piezo-thermomeca

Active device : 60 μm x 30 μm x 2.2 mm

Experimental validation

Patented designs

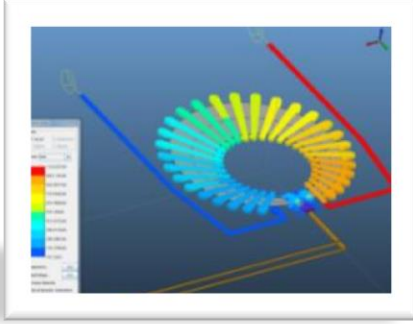
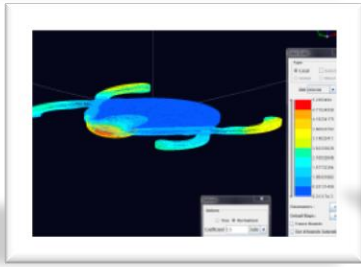
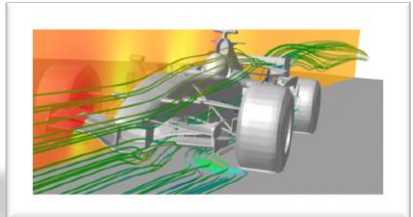
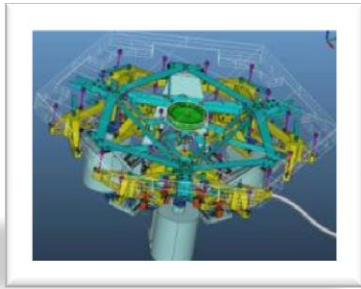
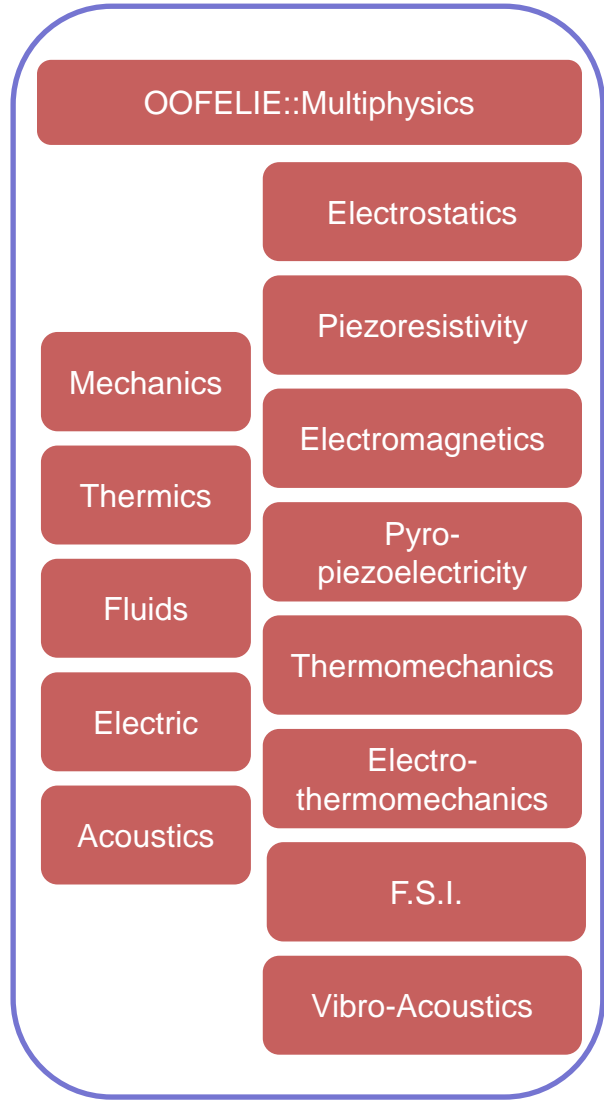
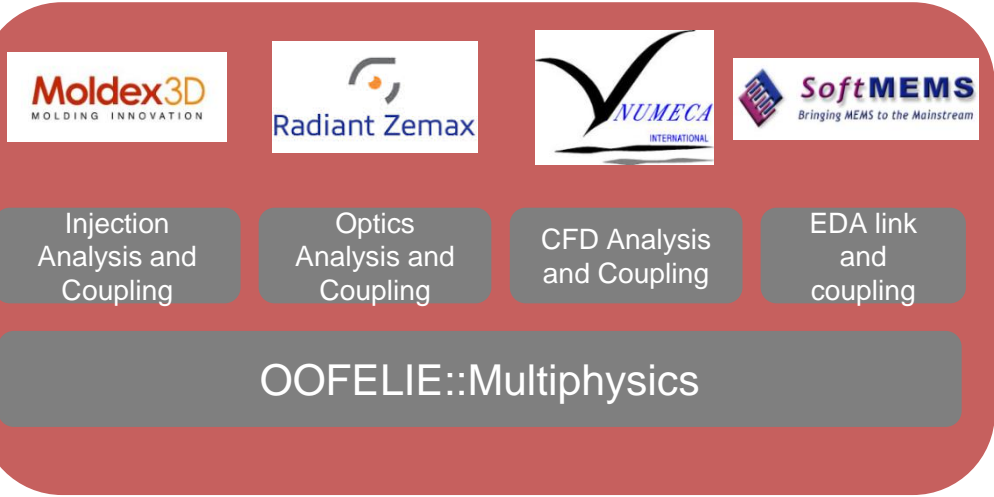
Licensed to defence industry

open engineering

THALES

Introduction

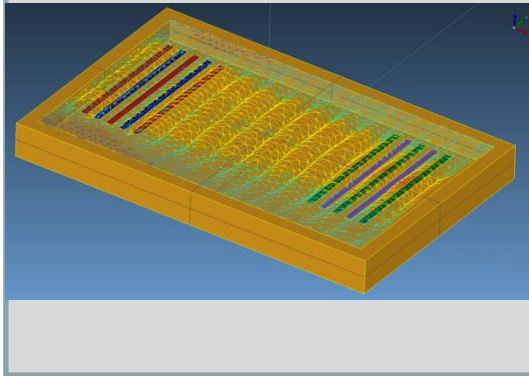
OOFELIE::Multiphysics

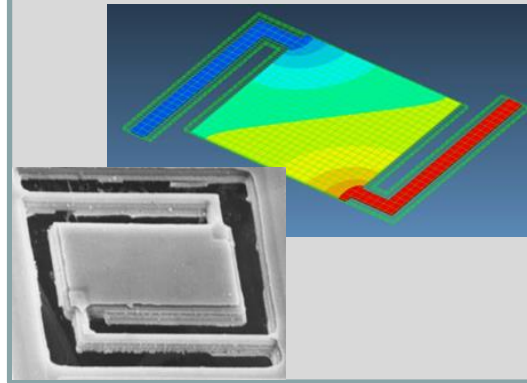
Introduction

General microsystems applications

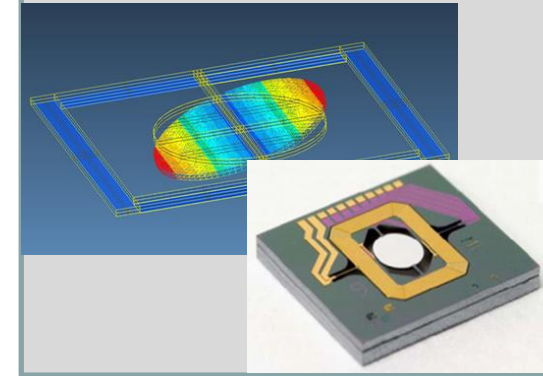
Gyrometer (SAW)



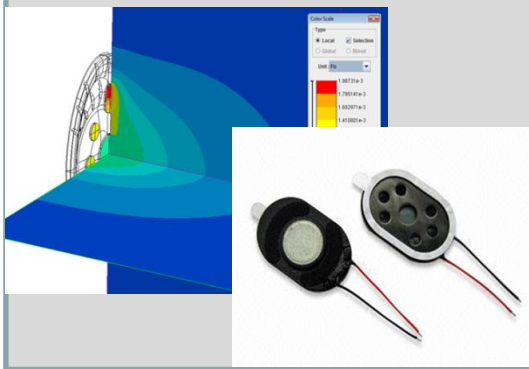
IR sensor



Micro-mirror



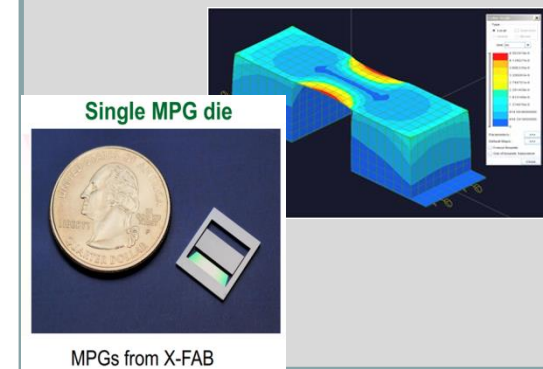
Micro-loudspeaker



Pressure sensor



Energy harvester



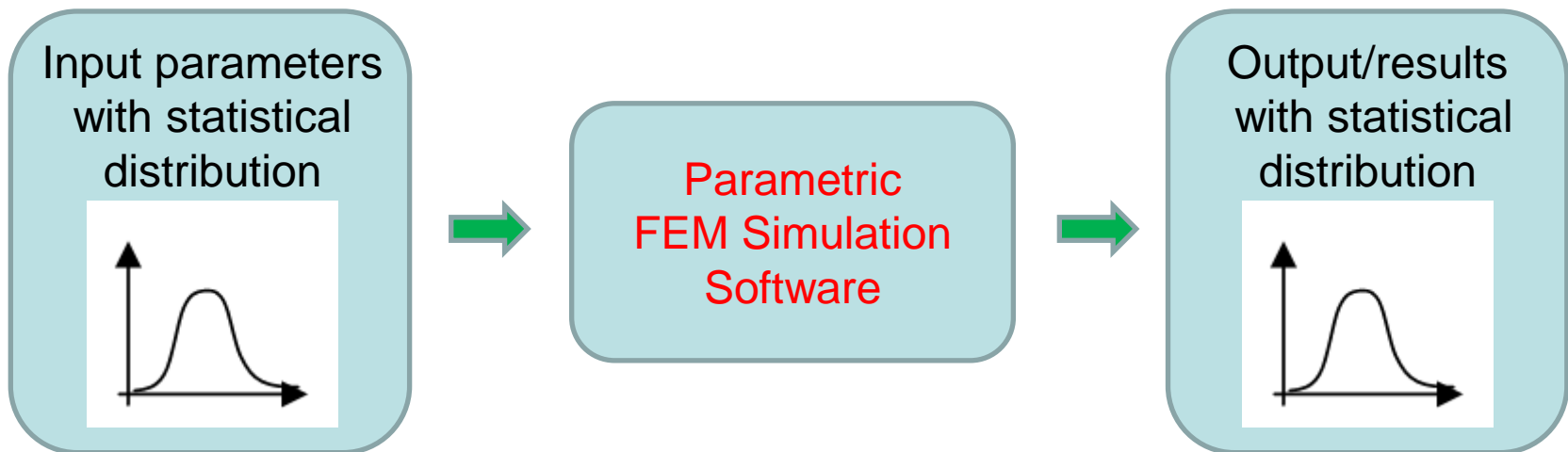
Introduction

Uncertainties quantification (1/2)

❑ Source of uncertainties in microsystems

- ❑ Material properties
- ❑ Dimensions
- ❑ Roughness
- ❑ Prestress from fab process
- ❑ ...

❑ General principle



Introduction

Uncertainties quantification (2/2)

❑ How to deal with these uncertainties in FEM software

❑ Non-intrusive methods

- ❑ General and easy to implement : like Monte Carlo methodology
... but CPU time expensive

❑ Intrusive methods

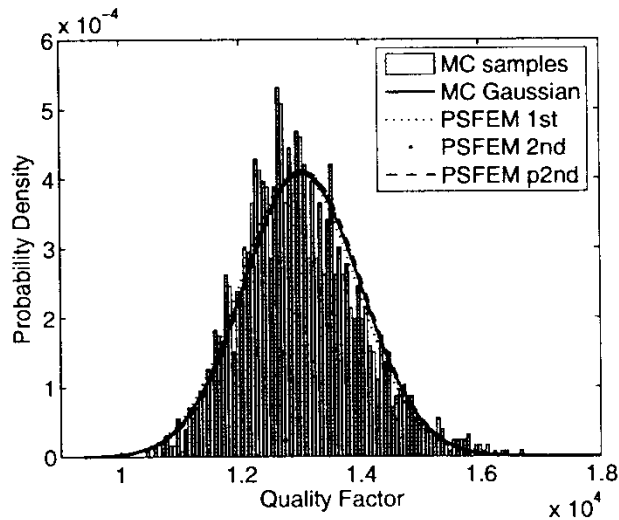
- ❑ Difficult to implement: like Stochastic FEM
... but CPU time efficient



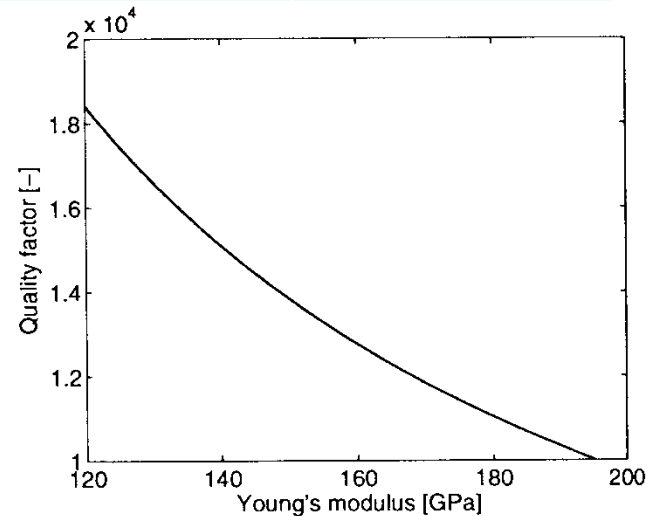
R & D on intrusive methods are performed at the present time in OOFELIE::Multiphysics software in the framework of several research projects

Monte Carlo simulation vs Stochastic FEM

Method	Mean (Q)	σ (Q)	CPU Time*
MC	13035	980	2005
PSFEM 1st	12967	971	1,02
PSFEM 2 nd	13037	971	1.16
PSFEM p2nd	13069	971	1.04



(a)



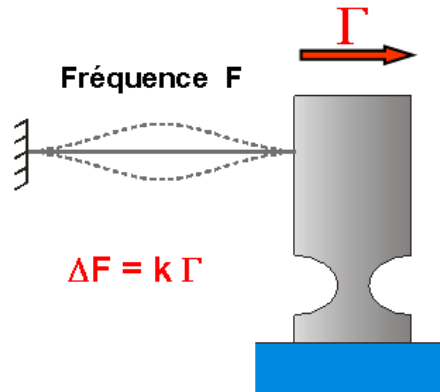
(b)

Detailed Applications

Accelerometer: VIA & DIVA

Vibrating Inertial Accelerometer

- Frequency shift due to axial stresses (guitar string effect)



Sensitive element (Quartz)

- Beam : 60 μm x 30 μm x 2.2 mm
- Proof mass : 5 mg
- Sensitive to orthogonal acceleration

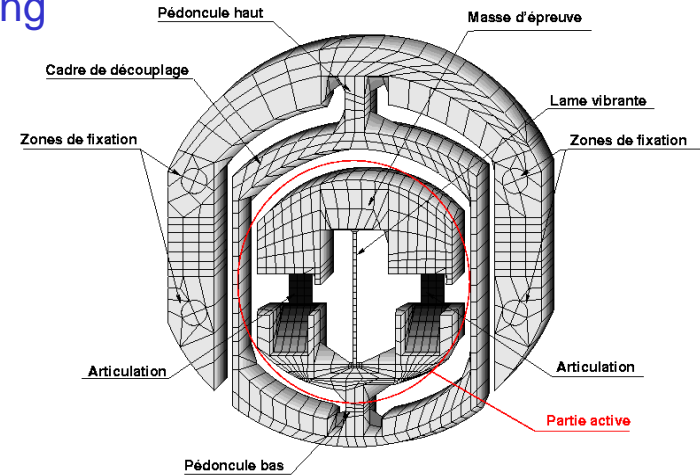
Detection system

- Piezoelectric excitation
- Electronic oscillator

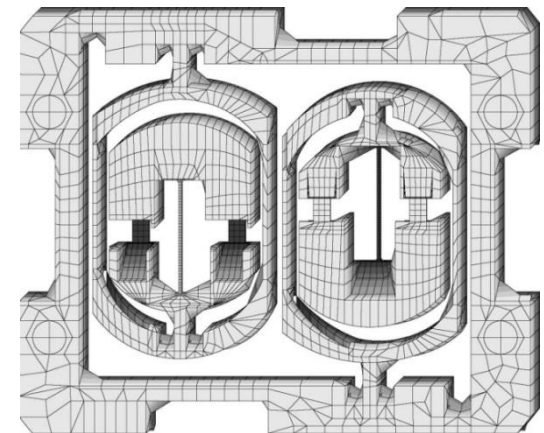
Monolithic differential accelerometer

- DIVA

VIA



DIVA



Detailed Applications – VIA & DIVA

High-Q resonators

❑ Oscillator accuracy

- ❑ High Q-factors required

❑ Energy dissipation

❑ Gas damping

- ❑ Vacuum (10^{-2} mbar) → neglected
- ❑ Could be considered using
 - ❑ BEM Stokes formulation
 - ❑ PLM viscous acoustic elements

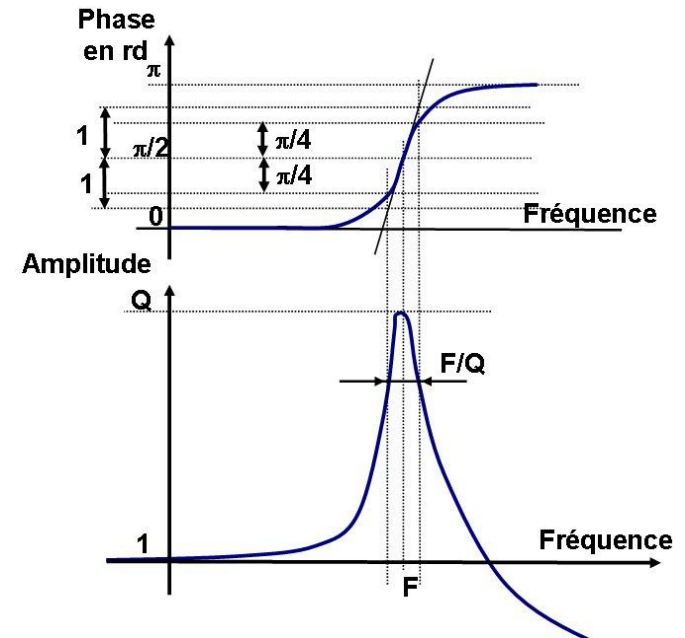
❑ Thermoelastic damping

- ❑ Main source of damping since monolithic structure

❑ Clamp losses

❑ Multiphysic analysis

- ❑ Mechanical, Electrical & thermal fields
- ❑ Piezoelectric, thermo-mechanical couplings (+pyro)



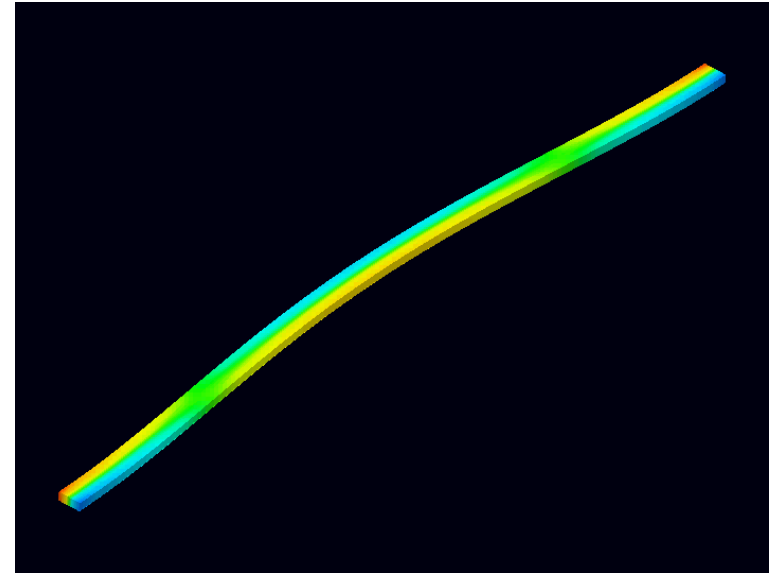
$$Q = 2\pi \cdot \frac{W_{Stored}}{W_{Dissipated}}$$

$$\Rightarrow \frac{1}{Q} = \frac{1}{Q_{gd}} + \frac{1}{Q_{ted}} + \frac{1}{Q_{cl}}$$

Detailed Applications – VIA & DIVA

Thermoelastic Damping

- ❑ **Bending mode**
 - ❑ Compression -> heating
 - ❑ Extension -> cooling
- ❑ **Irreversible heat flow**
 - ❑ Energy dissipation
 - ❑ Damping
- ❑ **Limitation of analytical model**
 - ❑ Anisotropic piezoelectric material
 - ❑ Complex 3D structure
 - ❑ Electrodes
 - ❑ ...
- ❑ **Modelling using OOFELIE**
 - ❑ Harmonic response analysis or complex modal analysis
 - ❑ Influence of piezoelectricity, electrodes
 - ❑ Good agreement with experimental results



	Q factor
Zener theory	16 580
OOFELIE: thermo-elastic	13 700
OOFELIE:piezo-thermo-elastic	13 090
Experimental characterisation	~13 000

S. Lepage et al., CANEUS 2006, Toulouse, France

Detailed Applications – VIA & DIVA

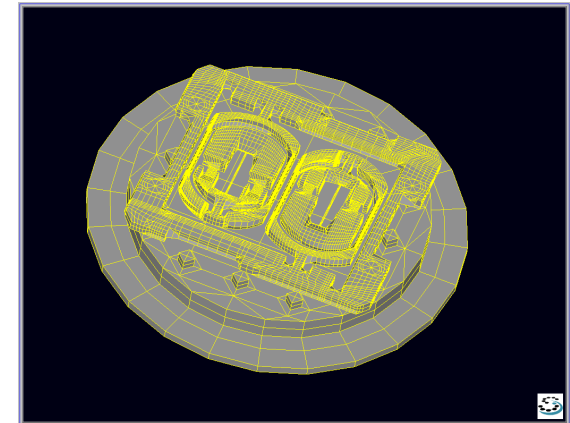
Insulating frame

Goals

- Limit energy losses through mounting parts
- Preserve resonance quality
- Protect resonance frequency from thermal stresses

Modal FEM Analysis

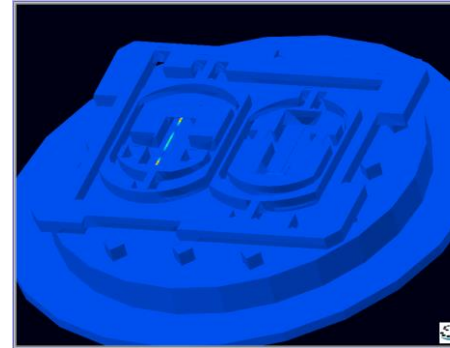
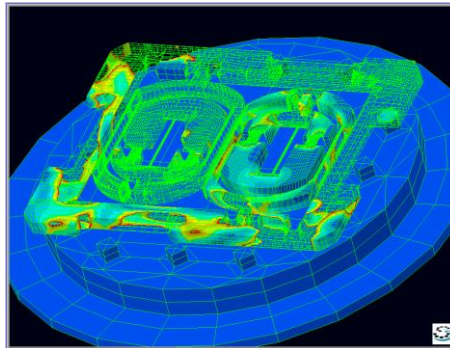
- Model quartz structure + TO8 base
- Evaluation of the strain energy dissipated in the base



→ Less than 10^{-8} of total vibrating energy in mounting parts

→ $Q_{\text{decoupling}} > 10^8$

→ Can be neglected because $Q_{\text{ted}} = 13000$

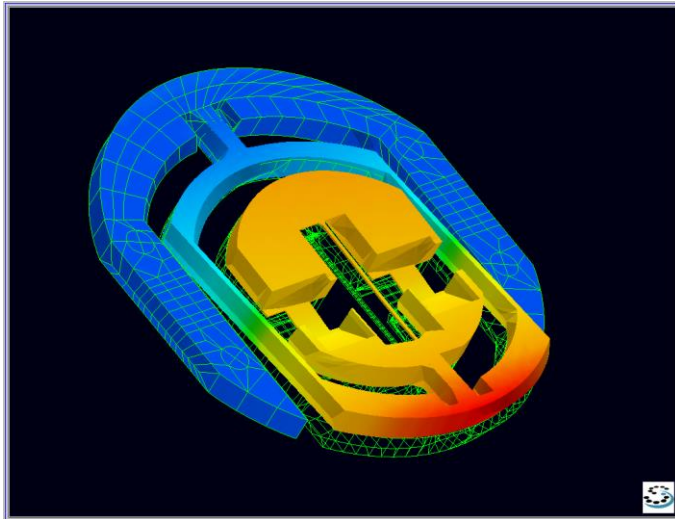


NOTE: more accurate computation of Q_{cl} could be performed using PML elements

Detailed Applications – VIA & DIVA

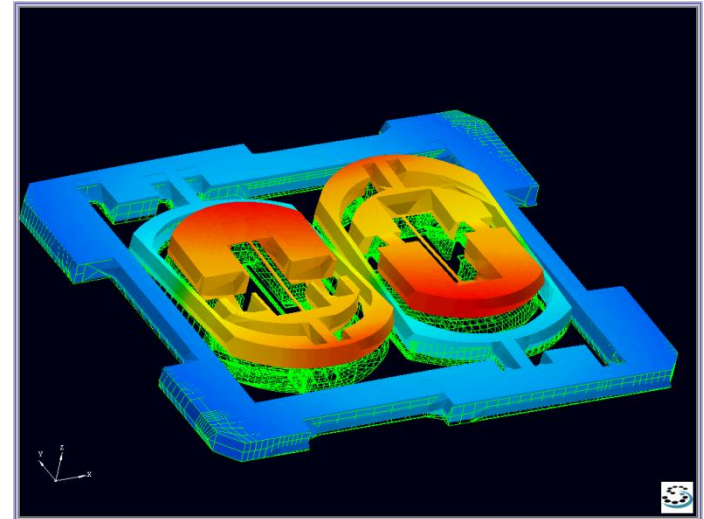
Scale factor estimation

- ❑ Stress generated by static acceleration
- ❑ Modal analysis with static pre-stress
- ❑ Evaluation of the frequency shift due to acceleration



Numerical scale factor : 12.6 Hz/g

Experimental S.F. : ~ 12.5 Hz/g



Numerical scale factor : 31.9 Hz/g

Experimental S.F. : ~ 30.5 Hz/g

Detailed Applications – VIA & DIVA

Electrical behaviour (1/2)

Equivalent electrical model

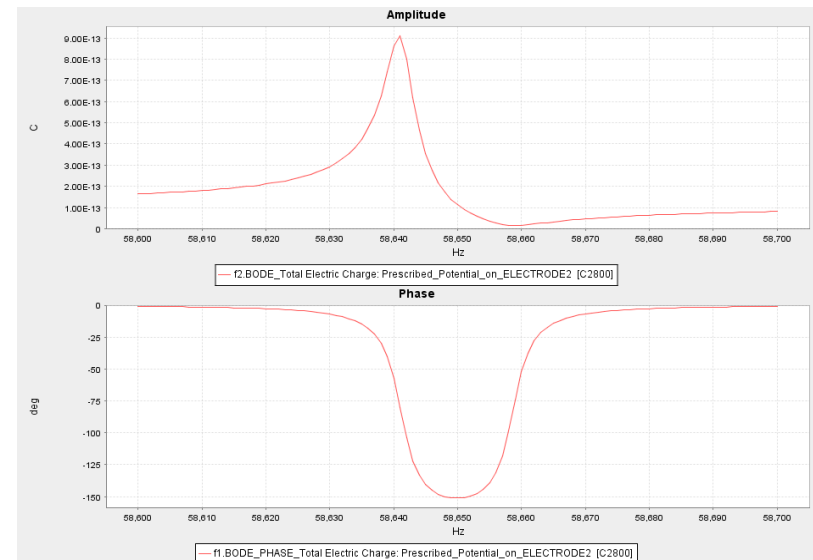
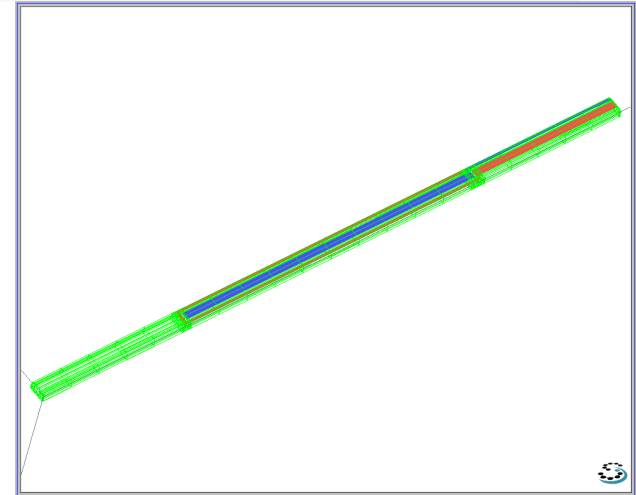
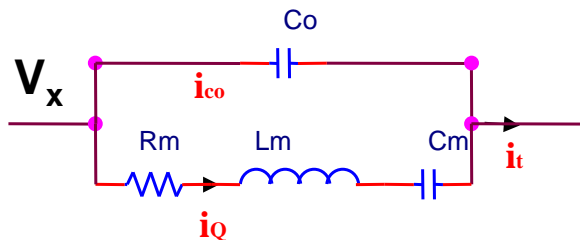
- C_0 : Capacitance
- R_m, L_m, C_m : motional parameters.

Influence on electronic oscillator

Piezoelectric FEM analysis

- Electrical response of the transducer
- Motional parameters
 - C_0 # 1 pF
 - R_m # 3 M Ω
 - Good agreement with experiment

Phase shift induced by C_0



Detailed Applications – VIA & DIVA

Electrical behaviour (2/2)

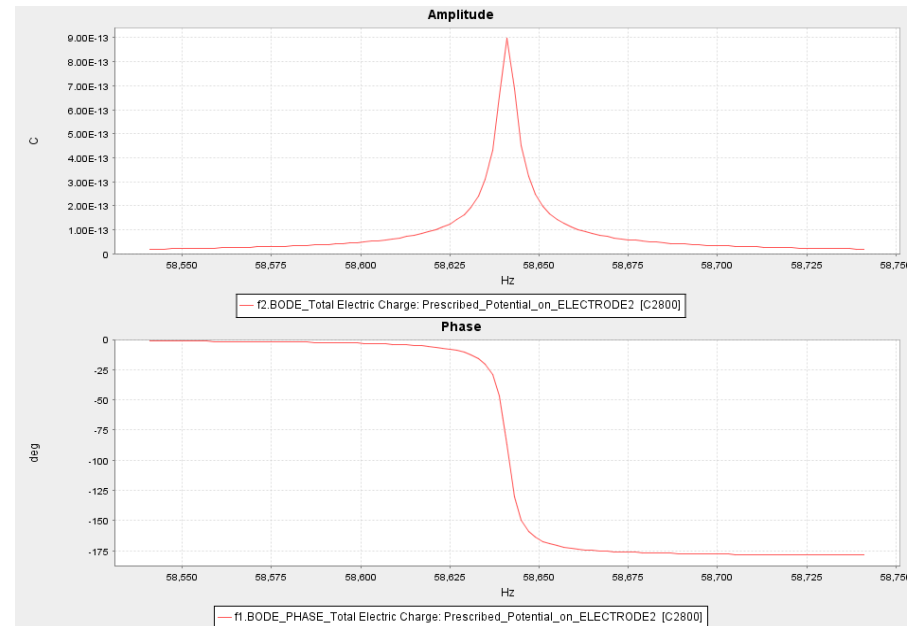
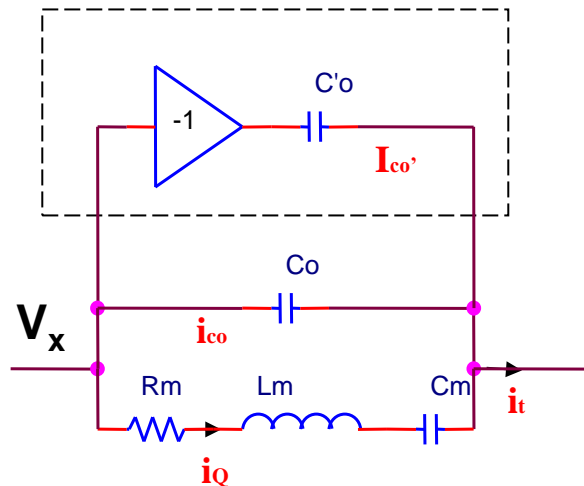
□ Influence of external electrical impedance

- Inter electrode capacitance cancellation

□ Impact of the electronic circuit on the transducer behavior

- Phase shift cancelled
- Same quality factor

□ Better response of the transducer



Detailed Applications – VIA & DIVA

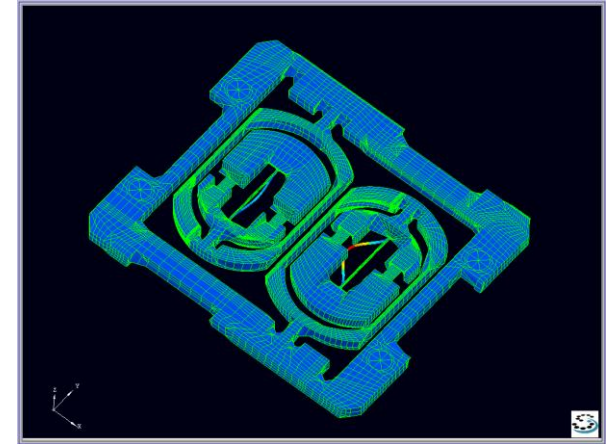
DIVA: Lock-in phenomena

❑ Lock-in

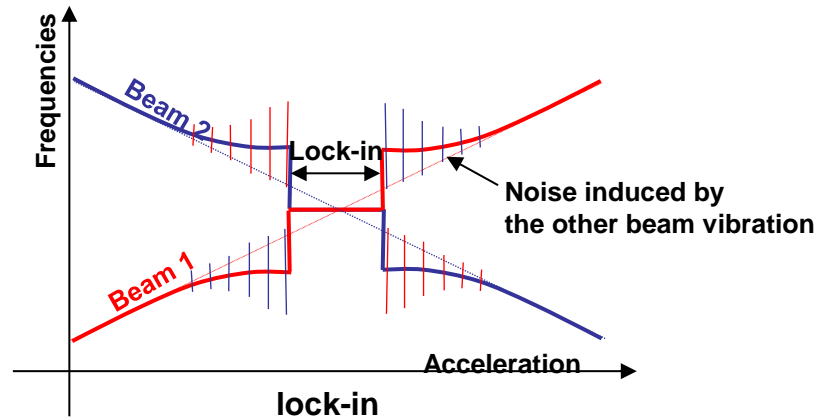
- ❑ Mechanical coupling between resonators
- ❑ Same resonance frequencies
- ❑ Blind zone

❑ Specific optimization by FEM

- ❑ Decoupling frame optimization
- ❑ Reducing vibrating energy transfer between resonators



❑ Reduction of the blind zone to 1 mg

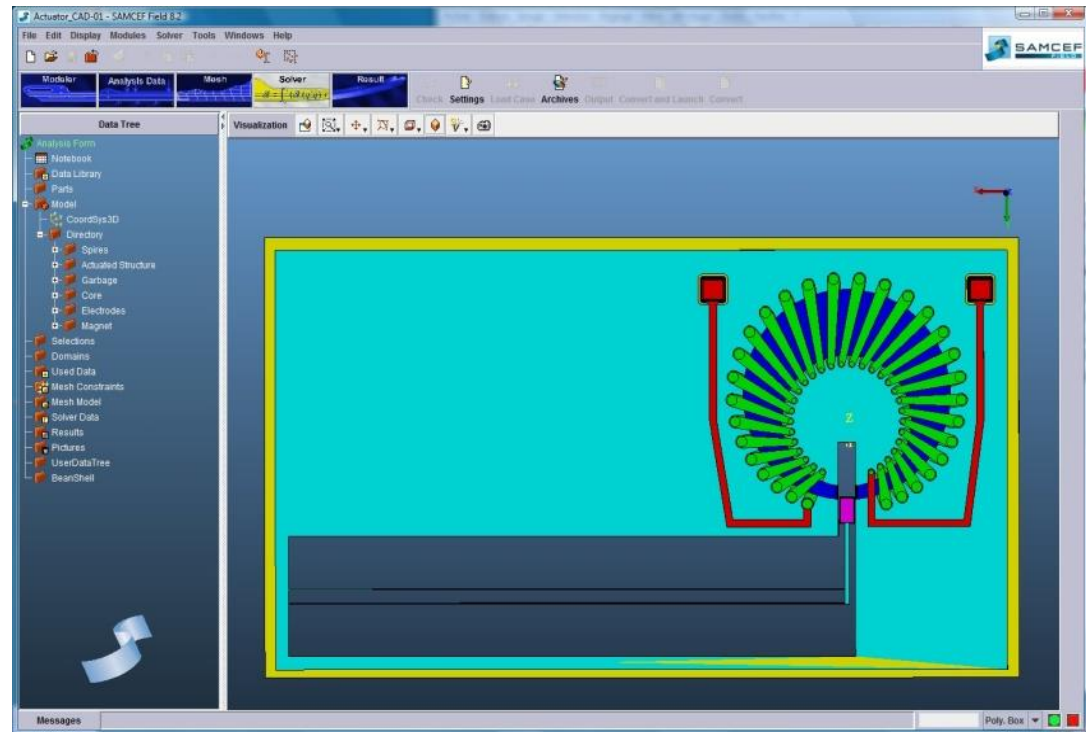
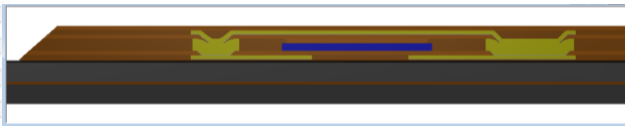
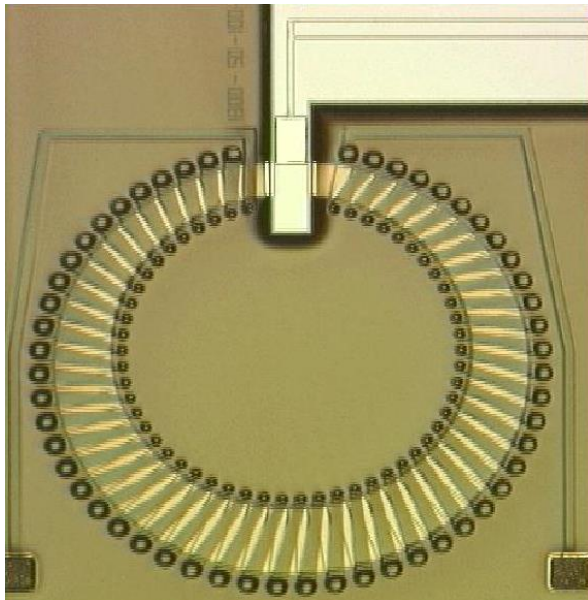


Detailed Applications

MEMS Electromagnetic actuator

Electromagnetic Actuator

- ❑ Based on 25 μm thick SOI
- ❑ Magnetic core and plunger made of 4 μm electroplated soft magnetic permalloy - NiFe (80/20)
- ❑ Windings are realized by electroplating 2 μm of Copper.
- ❑ Isolation and planarization based on polymer deposition



Detailed Applications – MEMS Electromagnetic actuator

Simulation methodology

❑ Basic mutiphysic analysis

- ❑ Non linear fully coupled analysis
 - CPU time expensive
- ❑ Large displacement of the plunger
 - remeshing → CPU time expensive

❑ Hypothesis

- ❑ no eddy current in the system

❑ New efficient simulation strategy

- ❑ Reduced Order Model (ROM) construction of the electromagnetic actuation part with a succession of magnetostatic analyses
- ❑ Use of generated ROM in a full 3D structural model
 - ❑ NL Static analysis
 - ❑ NL Transient analysis

Detailed Applications - MEMS Electromagnetic actuator

Electromagnetic actuation ROM generation

Construction of an EM parametric model in OOFELIE

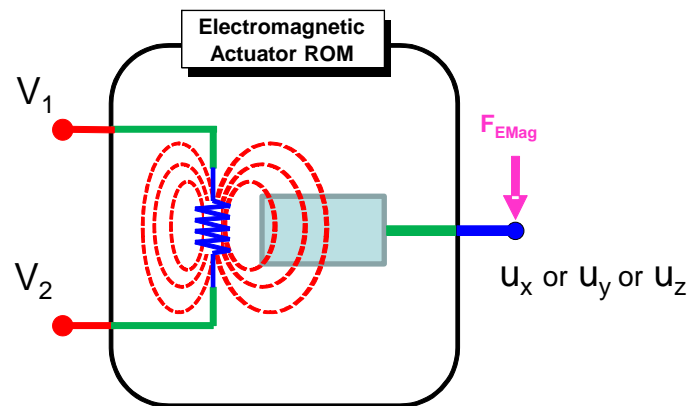
- u: position/displacement of the plunger in the considered direction
- i: current injected in the coil

+ extraction of resistivity of « coil » : R

Performing several NL magnetostatic analyses

- Batch computation for a grid of values for u and i
- For each couple (u,i)
 - Extraction of electromagnetic force on the plunger: $F(u,i)$
 - Extraction of secant inductance at the coil: $L(u,i)$

Construction of polynomial expressions for $F(u,i)$ and $L(u,i)$ that will be used in the 3 nodes emag actuation ROM



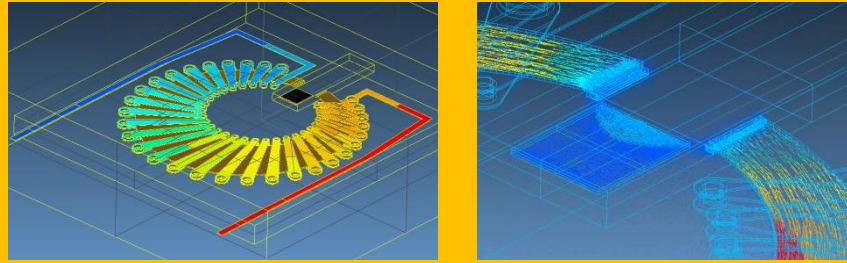
$$F(u, i)$$

$$V_1 - V_2 = R i + \frac{d(L(u, i) i)}{dt}$$

Detailed Applications - MEMS Electromagnetic actuator

Electromagnetic ROM generation

Sampling configuration space ($u=u_1, \dots, u_N$)



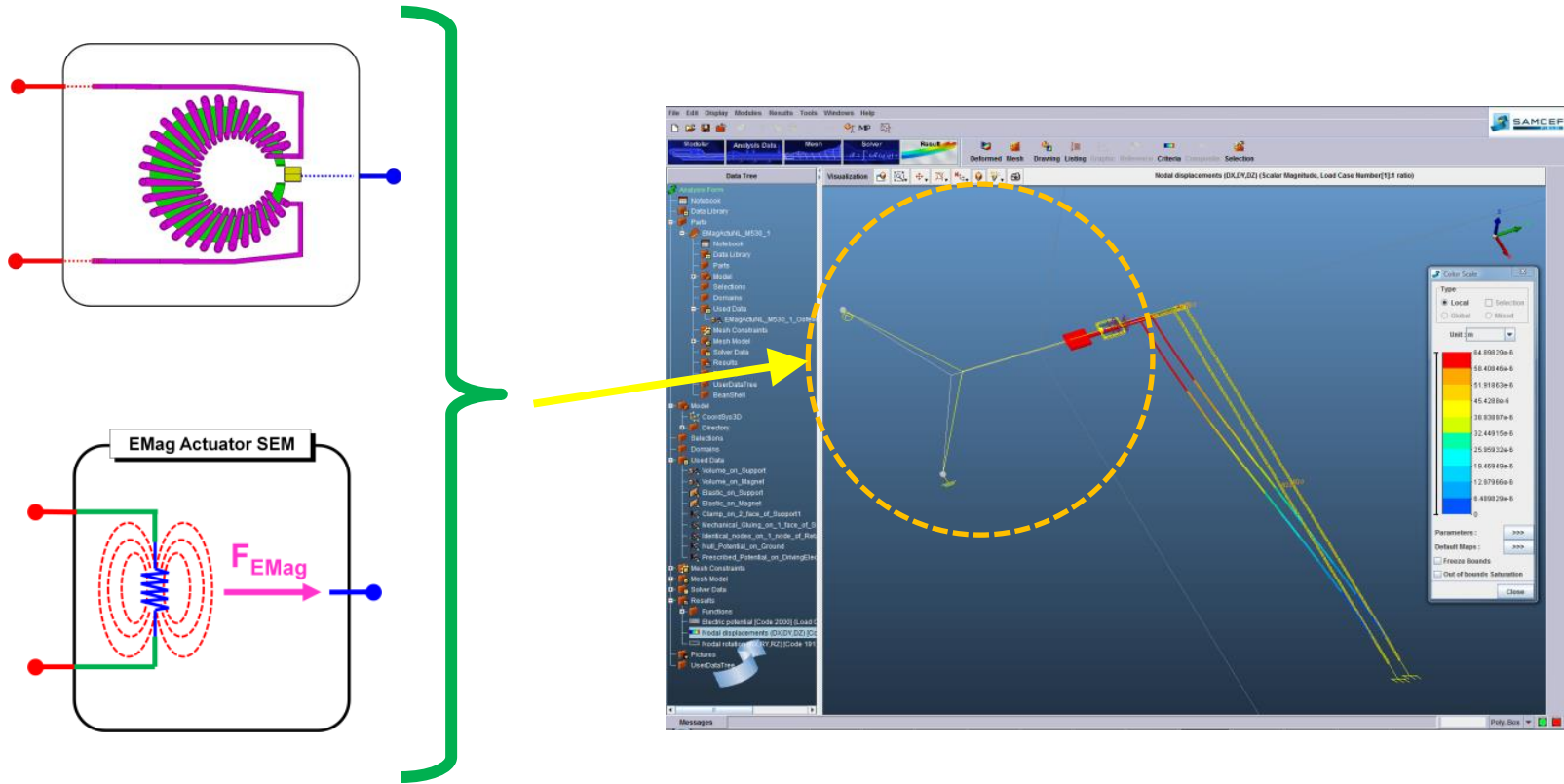
$L(u, i_1)$ $F(u, i_1)$
...
 $L(u, i_M)$ $F(u, i_M)$

Building polynomial expression of $L(u, i)$ & $F(u, i)$

Building 3-nodes emag actuation ROM
+ introduction in a structural FEM model

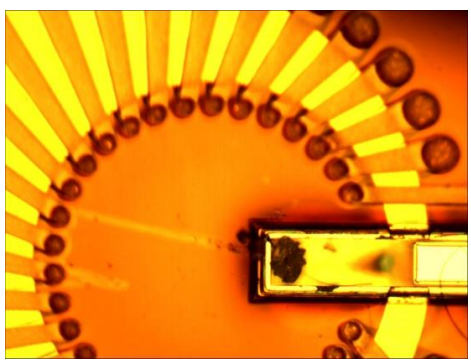
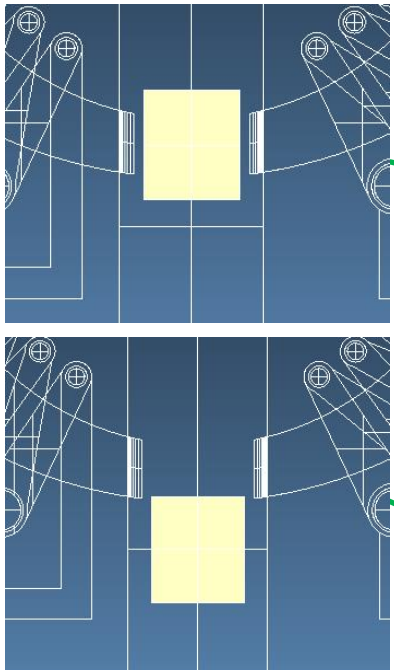
Detailed Applications - MEMS Electromagnetic actuator

Introduction of EMag ROM in structural model



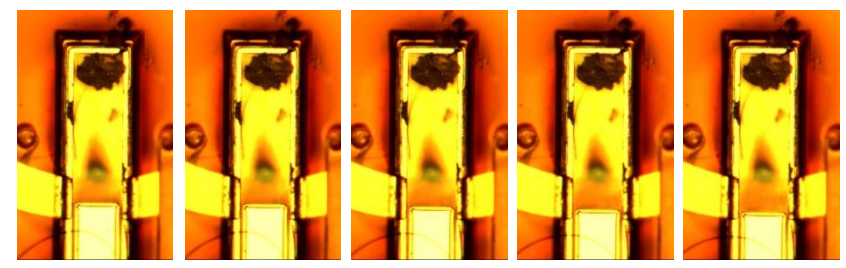
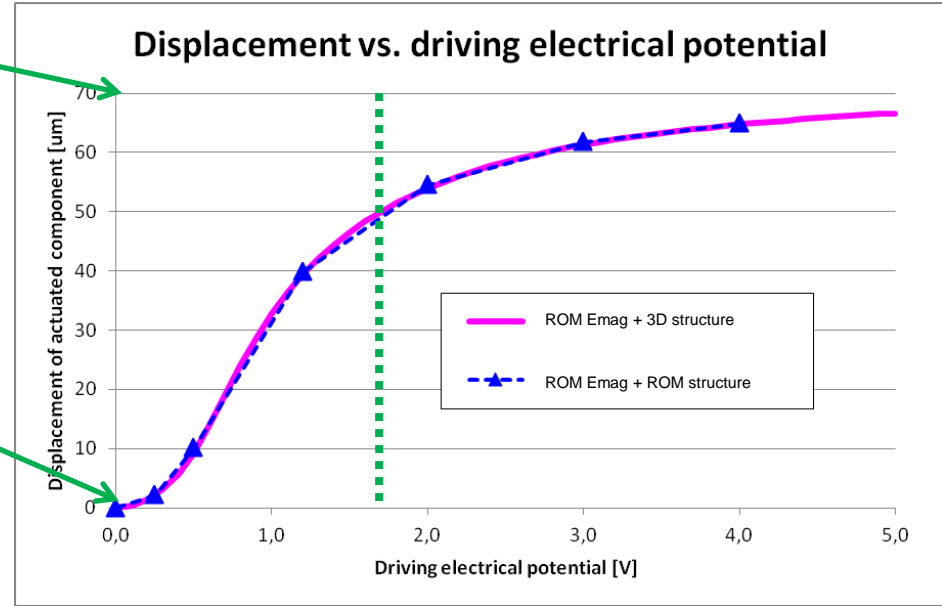
Detailed Applications - MEMS Electromagnetic actuator

Application – Static equilibrium



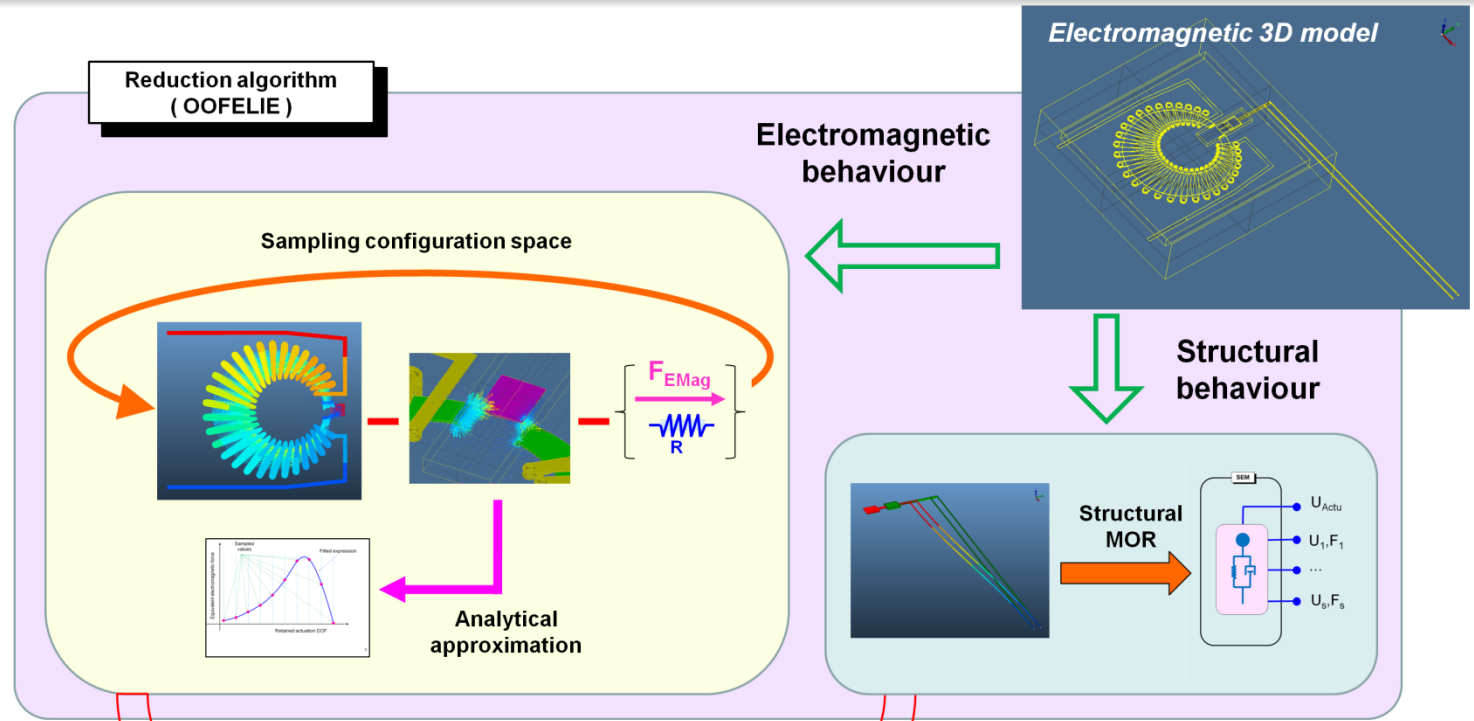
High sensitivity

Low sensitivity



1.01E+00
+1.007300E-03
+2.453700E-03
+4.940170E-03
+8.165530E-04
+8.347300E-03
+8.165530E-04
+8.347300E-03
+2.453700E-03
+4.940170E-03
+1.007300E-02
+9.247340E-03
+6.877220E-03
+2.175770E-02
+9.496330E+00
+1.177160E-02
+2.175770E-03
+9.496330E-03
+9.247340E-03
+6.877220E-03
+1.000000E+00
+1.000000E+00
+3.110801E+05
+4.079100E-08
+1.000000E+00
+1.328702E-08
+2.214724E-03
+4.079100E-08
+3.833747E-09
+0.000000E+00
+0.000000E+00
+3.032494E-09
+0.000000E+00
+0.000000E+00
+1.353102E+00


MOR for Electromagnetic Actuators Co-Simulation with IC



1.1E-01
-1.0E-03
+2.4E-03
+4.9E-03
+8.1E-03
+1.1E-02
+1.4E-02
+1.7E-02
+2.0E-02
+2.3E-02
+2.6E-02
+2.9E-02
+3.2E-02
+3.5E-02
+3.8E-02
+4.1E-02
+4.4E-02
+4.7E-02
+5.0E-02
+5.3E-02
+5.6E-02
+5.9E-02
+6.2E-02
+6.5E-02
+6.8E-02
+7.1E-02
+7.4E-02
+7.7E-02
+8.0E-02
+8.3E-02
+8.6E-02
+8.9E-02
+9.2E-02
+9.5E-02
+9.8E-02
+1.0E-01

HDL exportation

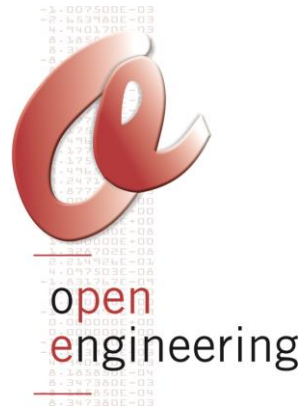
System level simulation



- ❑ **OOFELIE::Multiphysics simulation software**
 - ❑ Integrated CAE environment
 - ❑ Broad transducer domain coverage
 - ❑ Strongly coupled multiphysic approach for various MEMS applications
 - ❑ Electromagnetism
 - ❑ FSI
 - ❑ Piezo-thermomechanics (ex: ONERA VIA & DIVA)
 - ❑ Piezoresistive
 - ❑ ...
 - ❑ Efficient resolution technique using ROM/SEM with full 3D structural model
 - ❑ Strong coupling is conserved (ex: MEMS emag actuator)
 - ❑ Multiphysics FEA combined with ZEMAX® for MOEMS design
 - ❑ ITAR free

- ❑ **New developments in progress**
 - ❑ Stochastic FEM to take into account uncertainties aspects at the first stage of design process...

Thank you



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Fax: (+32/0)4.372.9321

Email: info@open-engineering.com

Website: www.open-engineering.com